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## Amendment to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

## **Listing of Claims:**

Claim 11 (currently amended): A method of producing high density arrays of target substances comprising sectioning a bundle of target-strands that has been stabilized by embedding the bundle in a [material] <u>matrix</u>;

where the target-strands comprise the target substances;

where the location of each target substance within the bundle is noted in a database; and,

where the sectioning results in a high density array.

Claim 12 (original): The method of claim 11, where the sectioning is performed with a cutting device selected from the group consisting of a microtome, laser, saw, and hot wire.

Claim 13 (previously presented): The method of claim 11, where the bundle sectioned comprises a target-strand selected from the group consisting of a cast rod of target substance, a target substance absorbed onto a glass fiber, a target substance absorbed onto a silk thread, a target substance attached to a polymer fiber, a target substance embedded in a porous rod, a target substance coated on a metal wire, a target substance contained within a matrix of gelatin, a line of a target substance drawn on a glass slide, a line of a target substance drawn on a membrane, and a target substance attached to the inside of a tube.

Claim 14 (original): The method of claim 11, where at least one of the target substances comprising the sectioned bundle of target-strands is selected from the group consisting of DNA, RNA, peptides, proteins, glycoproteins, lipoproteins, carbohydrates, lipids and immunoglobulins.

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Claim 15 (previously presented): The method of claim 11, where the sectioning is performed such that the resultant high density array has a thickness of from about 0.1  $\mu$ m to about 1.0 mm.

Claim 17 (canceled)

Claim 16 (original) The method of claim 11, where the sectioning is performed such that the resultant high density array has a thickness of greater than 50  $\mu$ m.

Claim 18 (currently amended): The method of claim [17] 18, where the [material] matrix is selected from the group consisting of epoxy, polypropylene and polystyrene.

Claim 19 (original): The method of claim 11, further including incorporating a material other than the target-strands into the bundle.

Claim 21 (withdrawn): The method of claim 11, where at least one of the target substances comprising the sectioned bundle of target-strands is selected from the group consisting of zinc, sulfur and gold.

Claim 22 (withdrawn): The method of claim 11, where at least one of the target substances comprising the sectioned bundle of target-strands is selected from the group consisting of viruses, chromosomes, mitochondria, prokaryotic cells, archaebacteria and eukaryotic cells.

Claim 23 (withdrawn): The method of claim 11, where at least one of the target substances comprising the sectioned bundle of target-strands is selected from the group consisting of ceramics, glasses, plastics, polymeric materials, wood, fabric and concrete.

Claim 24 (withdrawn): The method of claim 11, where at least one of the target substances comprising the sectioned bundle of target-strands is selected from the group consisting of semiconductors and superconductors

Claims 25-27 (canceled)

Claim 28 (previously presented): The method of claim 19, where the material is a secondary enzyme.

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Claim 29 (withdrawn): A method of interrogating a high density array, comprising producing a high density array according to the method of claim 11 and then interrogating the array.

Claim 30 (withdrawn): The method of claim 29, where interrogating comprises visual inspection.

Claim 31 (withdrawn): The method of claim 29, where interrogating comprises chemical deposition.

Claim 32 (withdrawn): The method of claim 29, where interrogating comprises electrical probing.

Claim 33 (withdrawn): The method of claim 29, where interrogating comprises magnetic sensing.

Claim 34 (withdrawn): The method of claim 29, where interrogating comprises mechanical sensing.

Claim 35 (new): The method of claim 19, where the material is a microbial inhibitor.

Claim 36 (new): The method of claim 19, where the material is an antioxidant.

Claim 37 (new): The method of claim 19, where the material is a nonfluorescent counterstain.

Claim 38 (new): The method of claim 19, where the material is a reflecting substance.